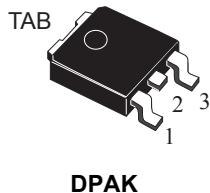


N-channel 500 V, 0.325 Ω typ., 10 A MDmesh™ M2 Power MOSFET in a DPAK package

Features



Order code	V _{DS}	R _{DS(on)max.}	I _D
STD12N50M2	500 V	0.38 Ω	10 A

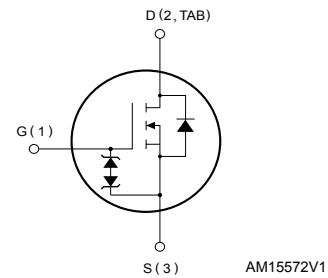
- Extremely low gate charge
- Excellent output capacitance (C_{oss}) profile
- 100% avalanche tested
- Zener-protected

Applications

- Switching applications

Description

This device is an N-channel Power MOSFET developed using MDmesh™ M2 technology. Thanks to its strip layout and an improved vertical structure, the device exhibits low on-resistance and optimized switching characteristics, rendering it suitable for the most demanding high efficiency converters.



Product status	
STD12N50M2	
Product summary	
Order code	
Marking	12N50M2
Package	DPAK
Packing	Tape and reel

1 Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{GS}	Gate-source voltage	± 30	V
I_D	Drain current (continuous) at $T_C = 25^\circ\text{C}$	10	A
I_D	Drain current (continuous) at $T_C = 100^\circ\text{C}$	7	A
$I_{DM}^{(1)}$	Drain current (pulsed)	40	A
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	85	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	15	V/ns
$dv/dt^{(3)}$	MOSFET dv/dt ruggedness	50	V/ns
T_j	Operating junction temperature range	-55 to 150	$^\circ\text{C}$
T_{stg}	Storage temperature range		

1. Pulse width limited by safe operating area.
2. $I_{SD} \leq 10 \text{ A}$, $di/dt \leq 400 \text{ A}/\mu\text{s}$; $V_{DS \text{ peak}} < V_{(BR)DSS}$; $V_{DD} = 400 \text{ V}$.
3. $V_{DS} \leq 400 \text{ V}$.

Table 2. Thermal data

Symbol	Parameter	Value	Unit
$R_{thj-case}$	Thermal resistance junction-case	1.47	$^\circ\text{C}/\text{W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb	50	$^\circ\text{C}/\text{W}$

1. When mounted on 1 inch² FR-4, 2 Oz copper board.

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not-repetitive (pulse width limited by T_j Max)	3.5	A
E_{AS}	Single pulse avalanche energy (starting $T_j = 25^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50 \text{ V}$)	204	mJ

2 Electrical characteristics

($T_{CASE} = 25^\circ\text{C}$ unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$I_D = 1 \text{ mA}, V_{GS} = 0 \text{ V}$	500			V
I_{DSS}	Zero gate voltage drain current	$V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA
		$V_{DS} = 500 \text{ V}, V_{GS} = 0 \text{ V}, T_C = 125^\circ\text{C}$ ⁽¹⁾			100	μA
I_{GSS}	Gate body leakage current	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 25 \text{ V}$			± 10	μA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$	2	3	4	V
$R_{DS(\text{on})}$	Static drain-source on resistance	$V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		0.325	0.38	Ω

- Defined by design, not subject to production test.

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 100 \text{ V}, f = 1 \text{ MHz}, V_{GS} = 0 \text{ V}$	-	550	-	pF
C_{oss}	Output capacitance			33		
C_{rss}	Reverse transfer capacitance			1		
$C_{oss \text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{GS} = 0 \text{ V}, V_{DS} = 0 \text{ to } 400 \text{ V}$	-	125	-	pF
R_g	Gate input resistance	$f = 1 \text{ MHz}$ open drain	-	6.8	-	Ω
Q_g	Total gate charge	$V_{DD} = 400 \text{ V}, I_D = 10 \text{ A}, V_{GS} = 0 \text{ to } 10 \text{ V}$ (see Figure 14. Test circuit for gate charge behavior)	-	15	-	nC
Q_{gs}	Gate-source charge			3		
Q_{gd}	Gate-drain charge			8.3		

- $C_{oss \text{ eq.}}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS} .

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 250 \text{ V}, I_D = 5 \text{ A}, R_G = 4.7 \Omega, V_{GS} = 10 \text{ V}$ (see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform)	-	13.5	-	ns
t_r	Rise time			10.5		
$t_{d(off)}$	Turn-off delay time			8		
t_f	Fall time			34.5		

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		10	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)				40	
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 10 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.6	V
t_{rr}	Reverse recovery time	$I_{SD} = 10 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 60 \text{ V}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	276	ns	
Q_{rr}	Reverse recovery charge			2.4		
I_{RRM}	Reverse recovery current			17.5		
t_{rr}	Reverse recovery time	$I_{SD} = 10 \text{ A}, dI/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 60 \text{ V}, T_j = 150 \text{ }^\circ\text{C}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	376	ns	
Q_{rr}	Reverse recovery charge			3.4		
I_{RRM}	Reverse recovery current			18.3		

1. Pulse width limited by safe operating area.
2. Pulsed: pulse duration = 300 μs , duty cycle 1.5%.

2.1 Electrical characteristics curves

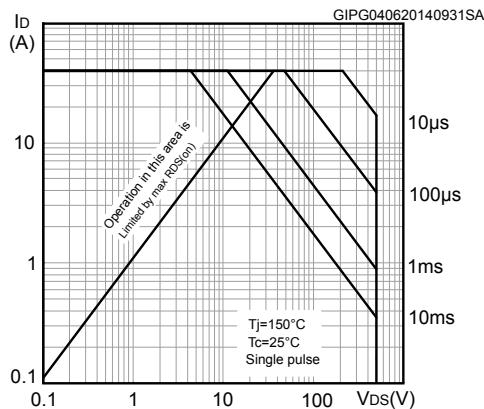
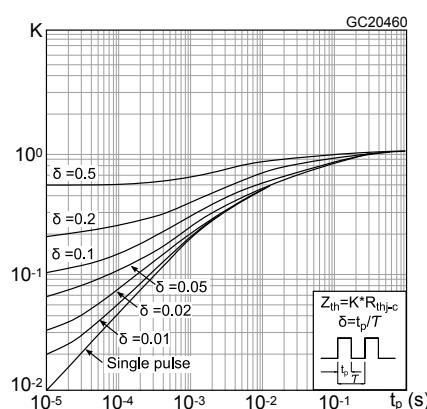
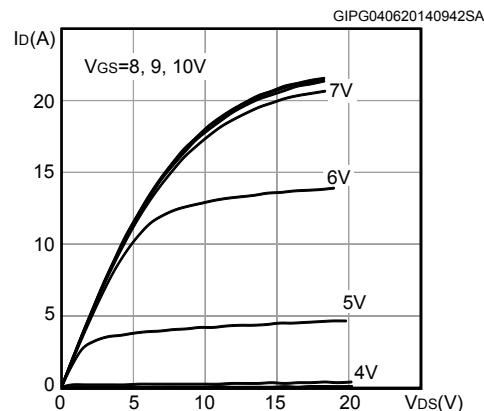
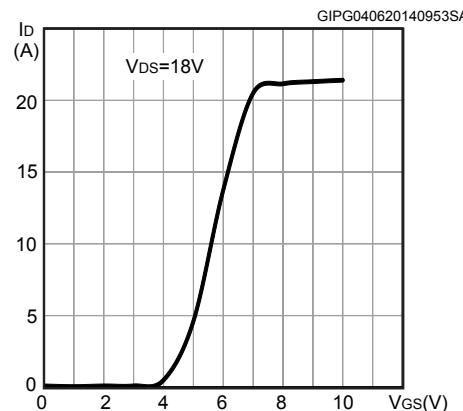
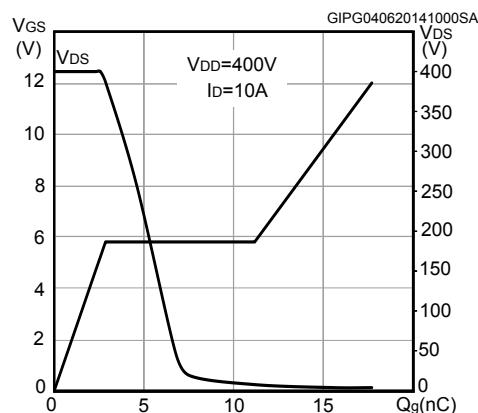
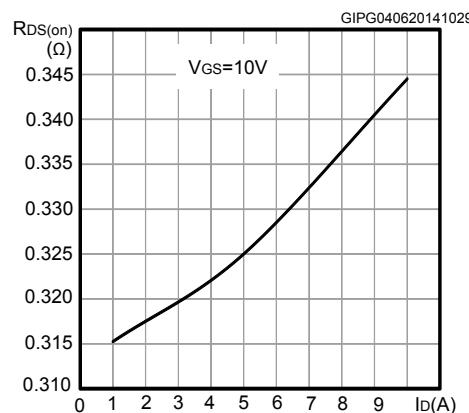
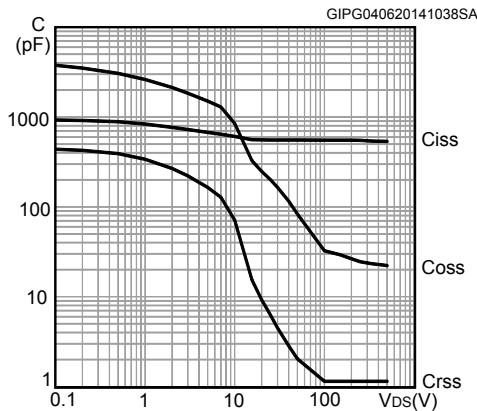
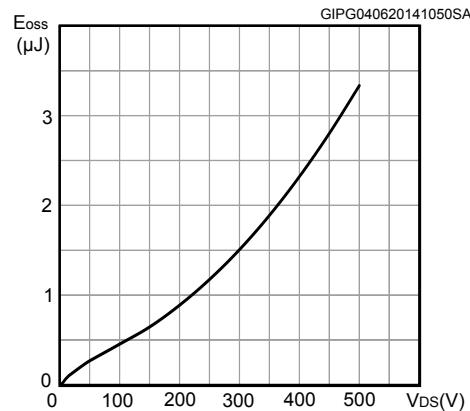
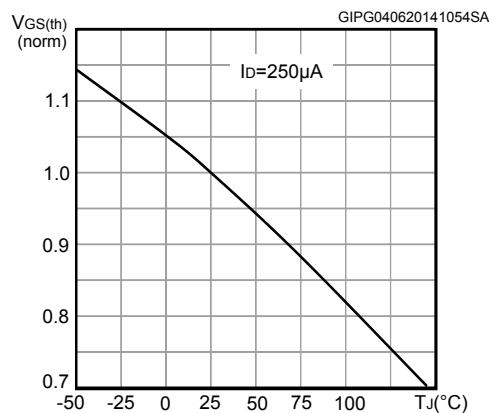
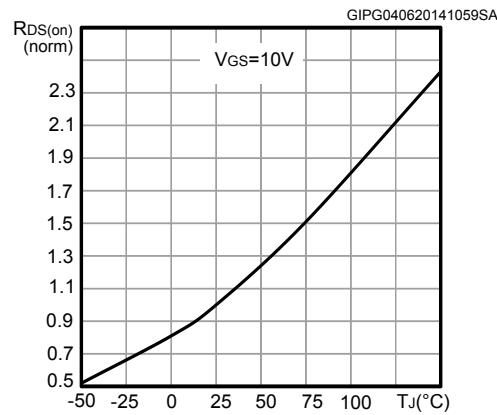
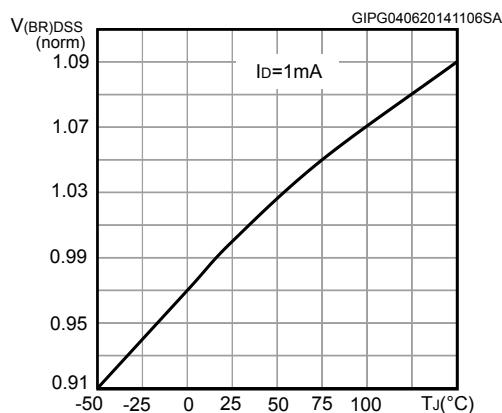
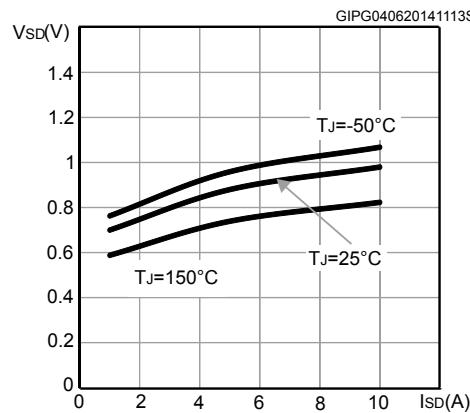
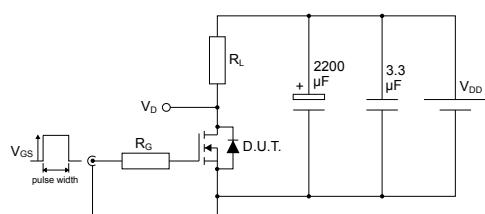
Figure 1. Safe operating area

Figure 2. Thermal impedance

Figure 3. Output characteristics

Figure 4. Transfer characteristics

Figure 5. Gate charge vs gate-source voltage

Figure 6. Static drain-source on resistance


Figure 7. Capacitance variations**Figure 8. Output capacitance stored energy****Figure 9. Normalized gate threshold voltage vs temperature****Figure 10. Normalized on-resistance vs temperature****Figure 11. Normalized $V_{(BR)DSS}$ vs temperature****Figure 12. Source-drain diode forward characteristics**

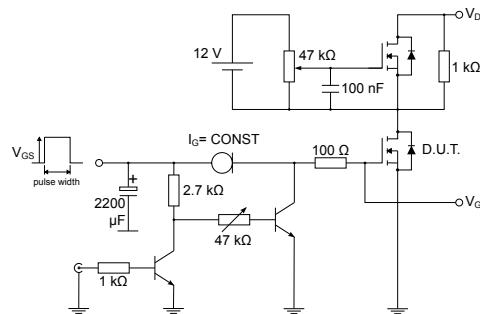
3 Test circuits

Figure 13. Test circuit for resistive load switching times



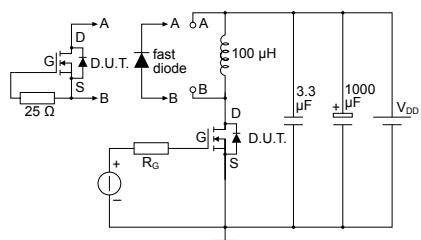
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Figure 14. Test circuit for gate charge behavior



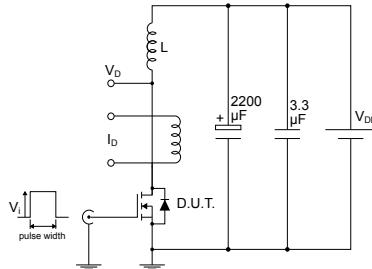
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Figure 15. Test circuit for inductive load switching and diode recovery times



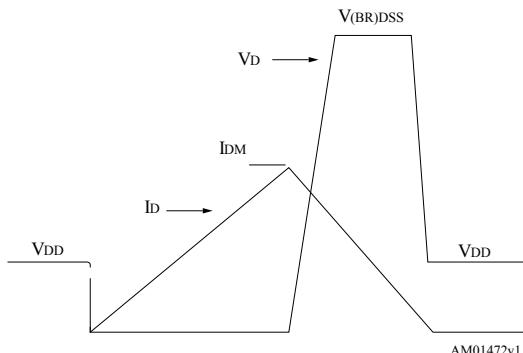
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Figure 16. Unclamped inductive load test circuit



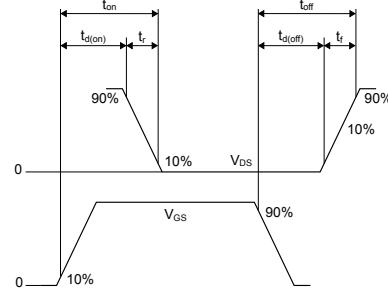
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Figure 17. Unclamped inductive waveform



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Figure 18. Switching time waveform



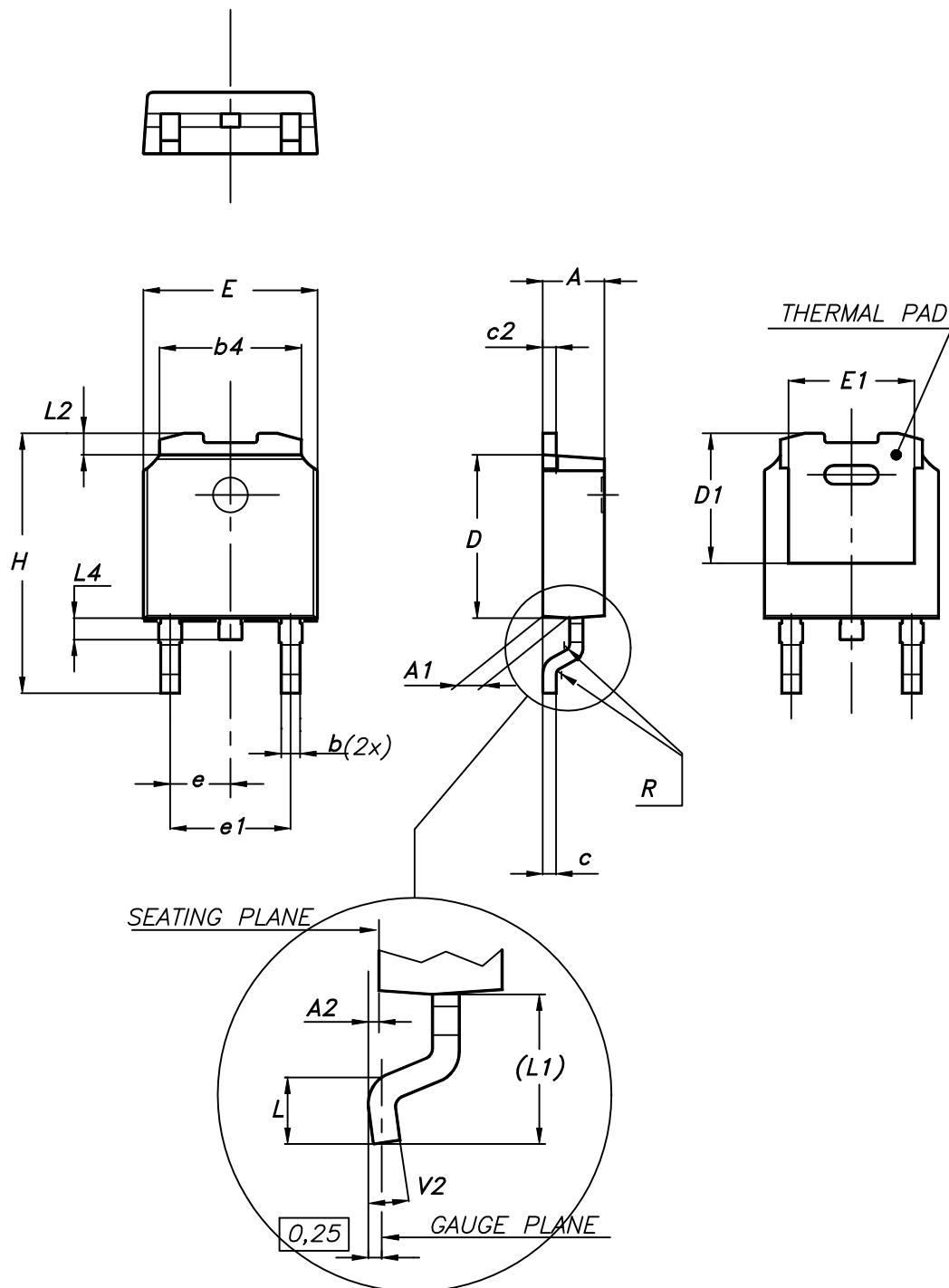
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4**Package information**

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 DPAK (TO-252) type A2 package information

Figure 19. DPAK (TO-252) type A2 package outline



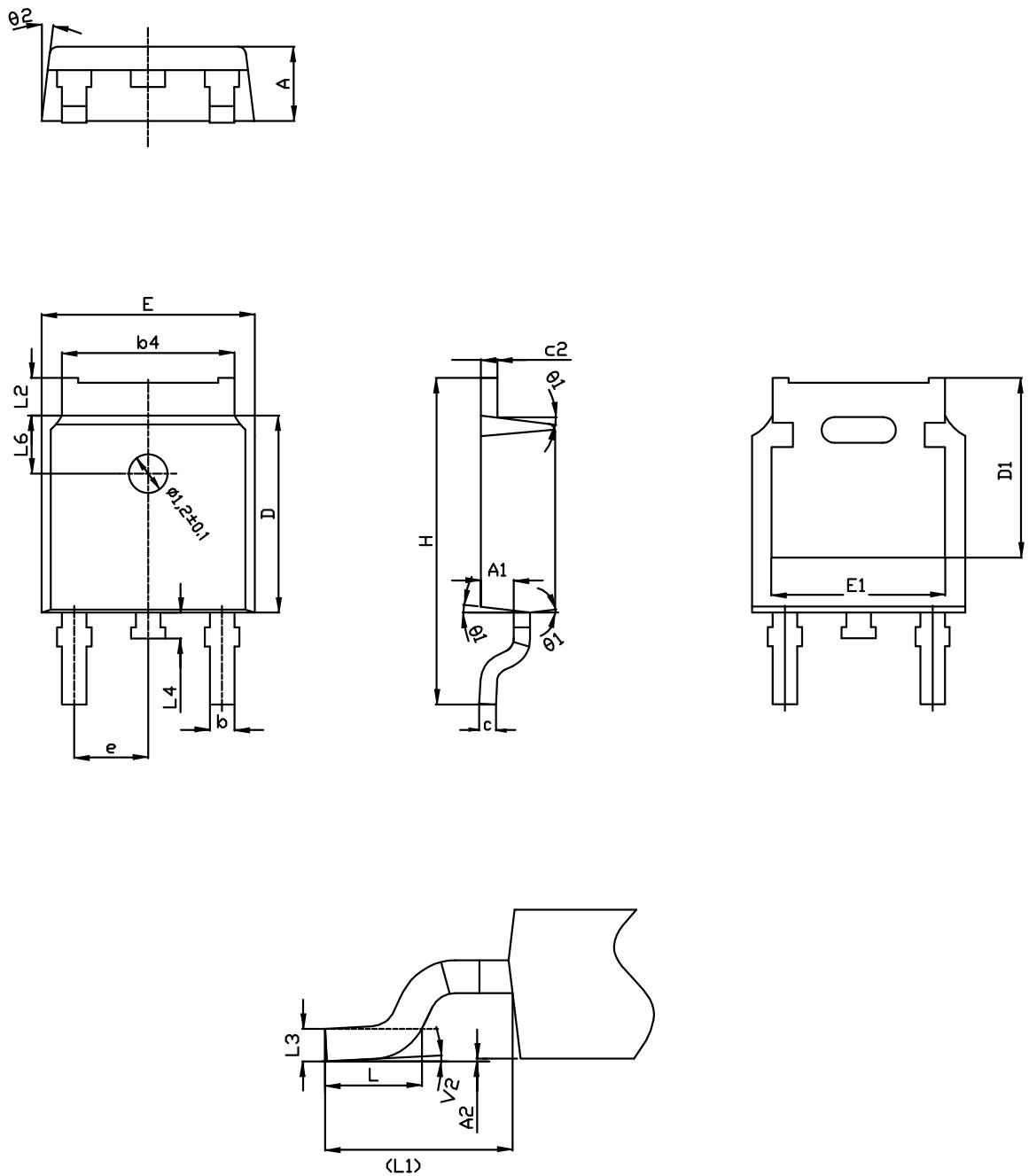
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Table 8. DPAK (TO-252) type A2 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	5.10	5.20	5.30
e	2.159	2.286	2.413
e1	4.445	4.572	4.699
H	9.35		10.10
L	1.00		1.50
L1	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

4.2 DPAK (TO-252) type C2 package information

Figure 20. DPAK (TO-252) type C2 package outline

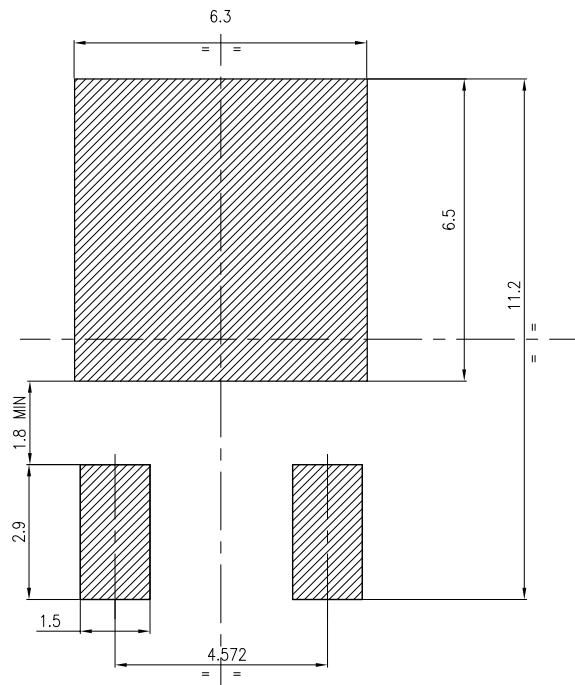


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Table 9. DPAK (TO-252) type C2 mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20	2.30	2.38
A1	0.90	1.01	1.10
A2	0.00		0.10
b	0.72		0.85
b4	5.13	5.33	5.46
c	0.47		0.60
c2	0.47		0.60
D	6.00	6.10	6.20
D1	5.10		5.60
E	6.50	6.60	6.70
E1	5.20		5.50
e	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1	2.90 REF		
L2	0.90		1.25
L3	0.51 BSC		
L4	0.60	0.80	1.00
L6	1.80 BSC		
θ1	5°	7°	9°
θ2	5°	7°	9°
V2	0°		8°

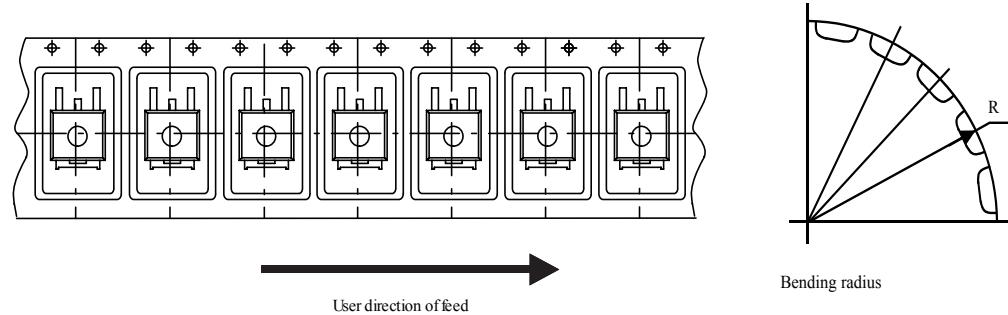
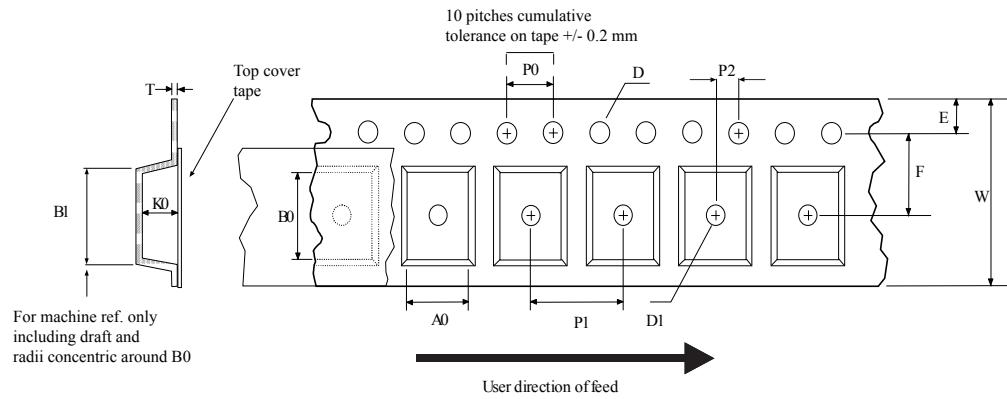
Figure 21. DPAK (TO-252) recommended footprint (dimensions are in mm)



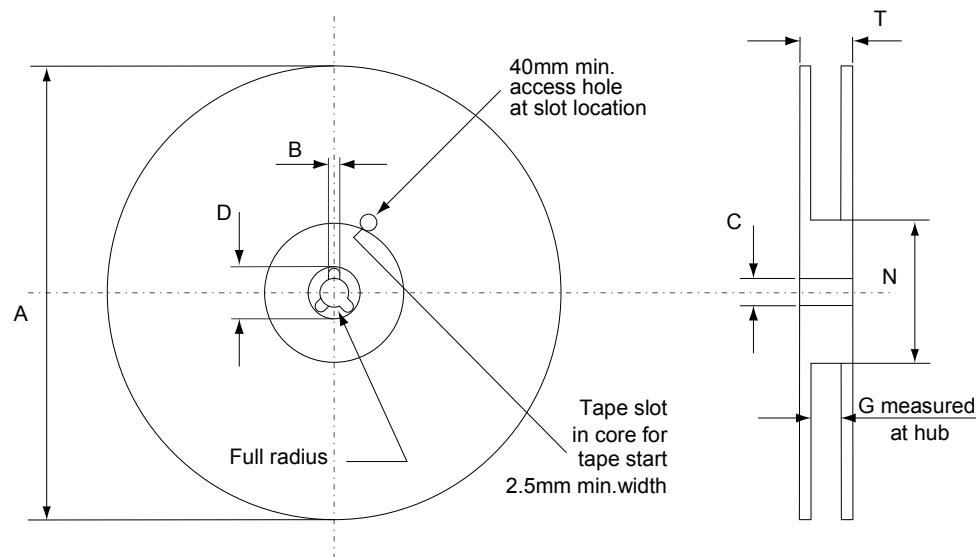
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4.3 DPAK (TO-252) packing information

Figure 22. DPAK (TO-252) tape outline



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Figure 23. DPAK (TO-252) reel outline

AM06038v1

Table 10. DPAK (TO-252) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

Revision history

Table 11. Document revision history

Date	Version	Changes
12-Mar-2014	1	First release.
17-Jun-2014	2	<ul style="list-style-type: none">– Modified: title– Modified: dv/dt values– Modified: values in Table 4– Modified: the entire typical values in <i>Table 5, 6, 7 and 8</i>– Added: <i>Section 2.1: Electrical characteristics (curves)</i>– Updated: <i>Section 4: Package mechanical data</i>– Minor text changes
12-Nov-2014	3	<ul style="list-style-type: none">– Document status promoted from preliminary to production data.– Updated title, features and description in cover page.
09-Dec-2014	4	<ul style="list-style-type: none">– Updated V_{GS} in <i>Table 2: Absolute maximum ratings</i>.– Updated <i>Section 4: Package mechanical data</i>.
02-May-2018	5	<p>Removed maturity status indication from cover page. The document status is production data.</p> <p>Updated <i>Section 2 Electrical characteristics</i> and <i>Section 4 Package information</i>.</p> <p>Minor text changes.</p>

Contents

1	Electrical ratings	2
2	Electrical characteristics.....	3
2.1	Electrical characteristics curves	5
3	Test circuits	7
4	Package information.....	8
4.1	DPAK (TO-252) type A2 package information	8
4.2	DPAK (TO-252) type C2 package information	10
4.3	DPAK (TO-252) packing information.....	13
	Revision history	16

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